MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

MFP5 4.1X4.4, 2.54P
CASE 100AM
ISSUE O

DATE 31 AUG 2016

LAND PATTERN RECOMMENDATION

NOTES:
A) NO STANDARD APPLIES TO THIS PACKAGE
B) ALL DIMENSIONS ARE IN MILLIMETERS.
C) DIMENSIONS ARE EXCLUSIVE OF BURRS,
   MOLD FLASH, AND TIE BAR EXTRUSION

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